

74AUP2G58

Low-power dual PCB configurable multiple function gate

Rev. 2 — 2 December 2015

Product data sheet

1. General description

The 74AUP2G58 is a dual configurable multiple function gate with Schmitt-trigger inputs. Each gate within the device can be configured as any of the following logic functions AND, OR, NAND, NOR, XOR, inverter and buffer; using the 3-bit input. All inputs can be connected directly to V_{CC} or GND.

This device ensures very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 5000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption; $I_{CC} = 0.9 \mu A$ (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial power-down mode operation
- Multiple package options
- Specified from $-40^{\circ}C$ to $+85^{\circ}C$ and $-40^{\circ}C$ to $+125^{\circ}C$



3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP2G58DP	−40 °C to +125 °C	TSSOP10	plastic thin shrink small outline package; 10 leads; body width 3 mm	SOT552-1
74AUP2G58GU	−40 °C to +125 °C	XQFN10	plastic, extremely thin quad flat package; no leads; 10 terminals; body 1.40 × 1.80 × 0.50 mm	SOT1160-1
74AUP2G58GF	−40 °C to +125 °C	XSON10	plastic extremely thin small outline package; no leads; 10 terminals; body 1.0 × 1.7 × 0.5 mm	SOT1081-2

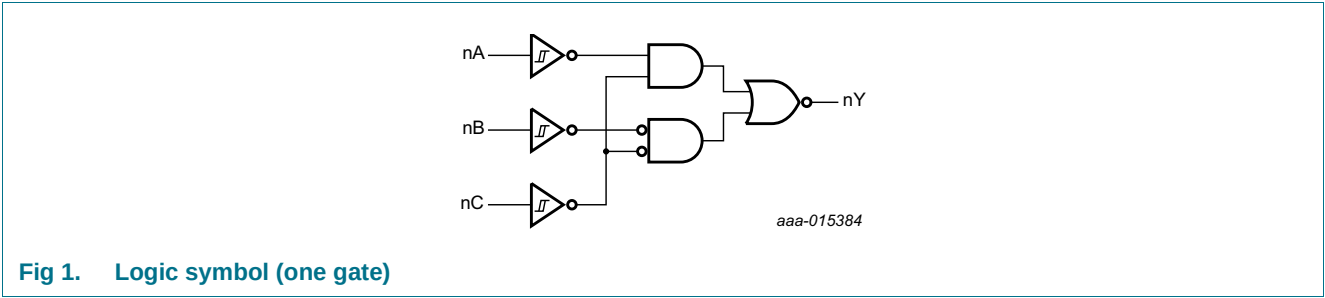
4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74AUP2G58DP	aK
74AUP2G58GU	aK
74AUP2G58GF	aK

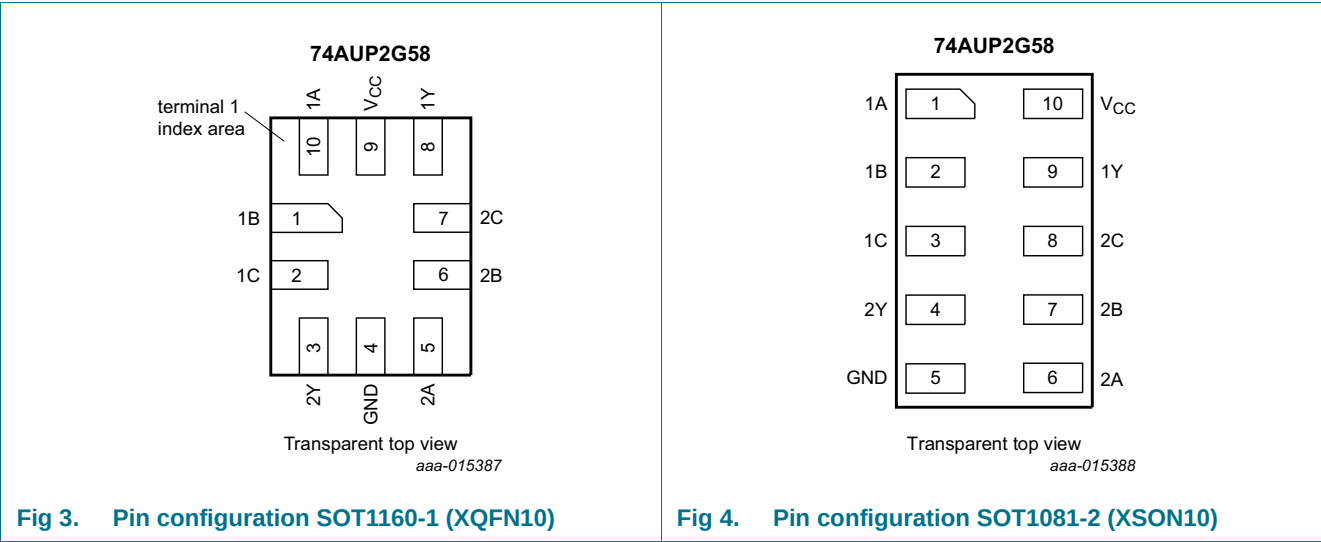
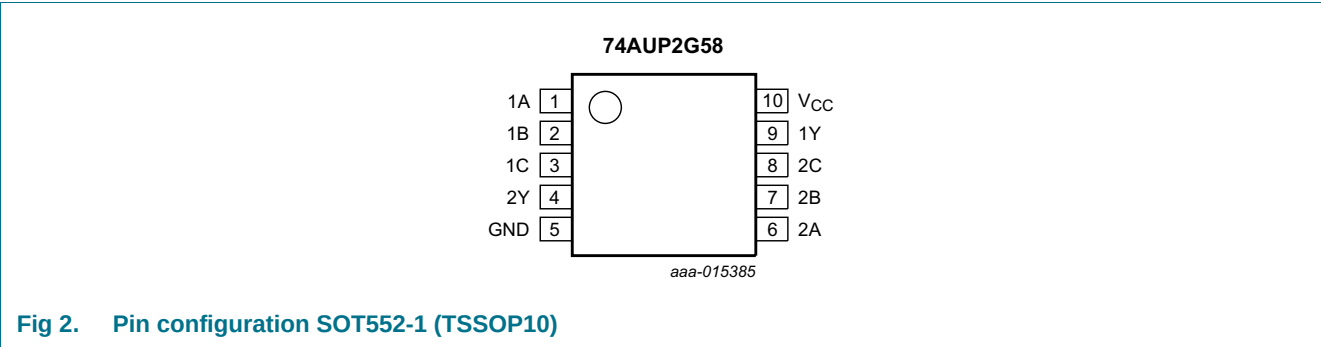
[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	SOT552-1 and SOT1081-2	SOT1160-1	
1A, 2A	1, 6	10, 5	data input
1B, 2B	2, 7	1, 6	data input
1C, 2C	3, 8	2, 7	data input
1Y, 2Y	9, 4	8, 3	data output
GND	5	4	ground (0 V)
V _{CC}	10	9	supply voltage

7. Functional description

Table 4. Function table^[1]

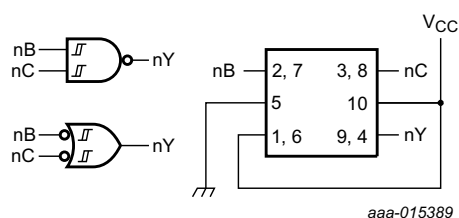
Input			Output
nC	nB	nA	nY
L	L	L	L
L	L	H	H
L	H	L	L
L	H	H	H
H	L	L	H
H	L	H	H
H	H	L	L
H	H	H	L

[1] H = HIGH voltage level; L = LOW voltage level.

7.1 Logic configurations

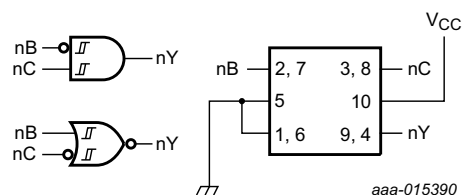
Table 5. Function selection table

Logic function	Figure
2-input NAND	see Figure 5
2-input NAND with both inputs inverted	see Figure 8
2-input AND with inverted input	see Figure 6 and Figure 7
2-input NOR with inverted input	see Figure 6 and Figure 7
2-input OR	see Figure 8
2-input OR with both inputs inverted	see Figure 5
2-input XOR	see Figure 9
Buffer	see Figure 10
Inverter	see Figure 11



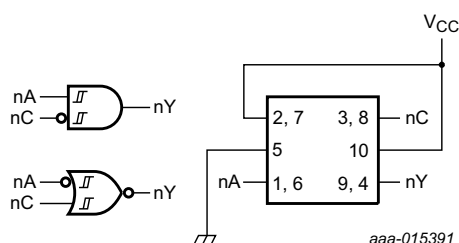
Pin numbers are not valid for SOT1160-1 package

Fig 5. 2-input NAND gate or 2-input OR with both inputs inverted



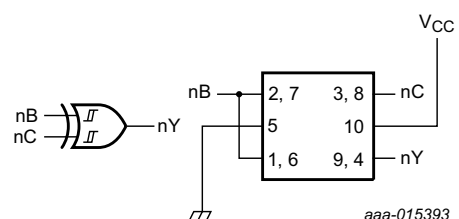
Pin numbers are not valid for SOT1160-1 package

Fig 6. 2-input AND gate with inverted B input or 2-input NOR gate with inverted C input



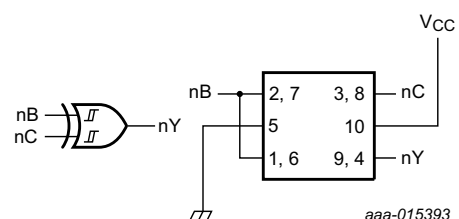
Pin numbers are not valid for SOT1160-1 package

Fig 7. 2-input AND gate with inverted C input or 2-input NOR gate with inverted A input



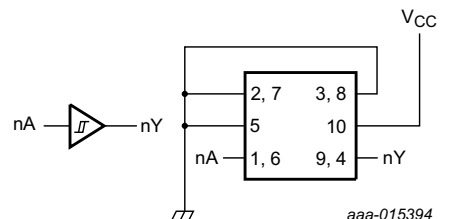
Pin numbers are not valid for SOT1160-1 package

Fig 8. 2-input OR gate or 2-input NAND gate with both inputs inverted



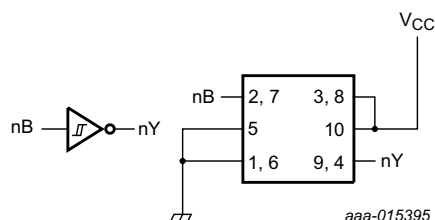
Pin numbers are not valid for SOT1160-1 package

Fig 9. 2-input XOR gate



Pin numbers are not valid for SOT1160-1 package

Fig 10. Buffer



Pin numbers are not valid for SOT1160-1 package

Fig 11. Inverter

8. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		-0.5	+4.6	V
I_{OK}	output clamping current	$V_O < 0$ V	-50	-	mA
V_O	output voltage	Active mode and Power-down mode	-0.5	+4.6	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 20	mA
I_{CC}	supply current		-	50	mA
I_{GND}	ground current		-50	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	-	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP10 package: above 125°C the value of P_{tot} derates linearly with 8.33 mW/K.

For XQFN10 (SOT1160-1) package: above 128 °C the value of P_{tot} derates linearly with 11.5 mW/K.

For XSON10 package: above 45 °C the value of P_{tot} derates linearly with 2.4 mW/K.

9. Recommended operating conditions

Table 7. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		0.8	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	Active mode	0	V_{CC}	V
		Power-down mode; $V_{CC} = 0$ V	0	3.6	V
T_{amb}	ambient temperature		-40	+125	°C

10. Static characteristics

Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = 25 °C						
V _{OH}	HIGH-level output voltage	V _I = V _{T+} or V _{T-}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.75 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.11	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.32	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	2.05	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.9	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.72	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.6	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{T+} or V _{T-}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.31	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.31	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.44	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.31	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.44	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.1	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.2	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.2	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	0.5	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	40	µA
C _I	input capacitance	V _I = GND or V _{CC} ; V _{CC} = 0 V to 3.6 V	-	1.1	-	pF
C _O	output capacitance	V _O = GND; V _{CC} = 0 V	-	1.7	-	pF

Table 8. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}$						
V_{OH}	HIGH-level output voltage	$V_I = V_{T+}$ or V_{T-}				
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 0.8\text{ V to } 3.6\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -1.1\text{ mA}; V_{CC} = 1.1\text{ V}$	$0.7 \times V_{CC}$	-	-	V
		$I_O = -1.7\text{ mA}; V_{CC} = 1.4\text{ V}$	1.03	-	-	V
		$I_O = -1.9\text{ mA}; V_{CC} = 1.65\text{ V}$	1.30	-	-	V
		$I_O = -2.3\text{ mA}; V_{CC} = 2.3\text{ V}$	1.97	-	-	V
		$I_O = -3.1\text{ mA}; V_{CC} = 2.3\text{ V}$	1.85	-	-	V
		$I_O = -2.7\text{ mA}; V_{CC} = 3.0\text{ V}$	2.67	-	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	2.55	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{T+}$ or V_{T-}				
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 0.8\text{ V to } 3.6\text{ V}$	-	-	0.1	V
		$I_O = 1.1\text{ mA}; V_{CC} = 1.1\text{ V}$	-	-	$0.3 \times V_{CC}$	V
		$I_O = 1.7\text{ mA}; V_{CC} = 1.4\text{ V}$	-	-	0.37	V
		$I_O = 1.9\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.35	V
		$I_O = 2.3\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.33	V
		$I_O = 3.1\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.45	V
		$I_O = 2.7\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.33	V
		$I_O = 4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.45	V
I_I	input leakage current	$V_I = \text{GND to } 3.6\text{ V}; V_{CC} = 0\text{ V to } 3.6\text{ V}$	-	-	± 0.5	μA
I_{OFF}	power-off leakage current	V_I or $V_O = 0\text{ V to } 3.6\text{ V}; V_{CC} = 0\text{ V}$	-	-	± 0.5	μA
ΔI_{OFF}	additional power-off leakage current	V_I or $V_O = 0\text{ V to } 3.6\text{ V}; V_{CC} = 0\text{ V to } 0.2\text{ V}$	-	-	± 0.6	μA
I_{CC}	supply current	$V_I = \text{GND or } V_{CC}; I_O = 0\text{ A}; V_{CC} = 0.8\text{ V to } 3.6\text{ V}$	-	-	0.9	μA
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.6\text{ V}; I_O = 0\text{ A}; V_{CC} = 3.3\text{ V}$	-	-	50	μA

Table 8. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{amb} = -40 °C to +125 °C						
V _{OH}	HIGH-level output voltage	V _I = V _{T+} or V _{T-}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.11	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.6 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	0.93	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.17	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.77	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.67	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.40	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.30	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{T+} or V _{T-}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.11	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.33 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.41	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.39	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.36	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.50	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.36	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.50	V
I _I	input leakage current	V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.75	µA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V	-	-	±0.75	µA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V	-	-	±0.75	µA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; V _{CC} = 0.8 V to 3.6 V	-	-	1.4	µA
ΔI _{CC}	additional supply current	V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	75	µA

11. Dynamic characteristics

Table 9. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 13](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C _L = 5 pF									
t _{pd}	propagation delay	nA, nB and nC to nY; see Figure 12							
		V _{CC} = 0.8 V	-	22.8	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.8	6.6	12.9	2.6	13.1	13.3	ns
		V _{CC} = 1.4 V to 1.6 V	2.4	4.8	7.6	2.4	8.3	8.6	ns
		V _{CC} = 1.65 V to 1.95 V	2.1	4.0	6.3	2.0	6.9	7.3	ns
		V _{CC} = 2.3 V to 2.7 V	2.0	3.2	4.6	1.8	5.1	5.4	ns
		V _{CC} = 3.0 V to 3.6 V	1.9	2.9	3.9	1.6	4.2	4.4	ns
C _L = 10 pF									
t _{pd}	propagation delay	nA, nB and nC to nY; see Figure 12							
		V _{CC} = 0.8 V	-	26.4	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.2	7.4	14.5	3.0	14.9	15.2	ns
		V _{CC} = 1.4 V to 1.6 V	2.7	5.4	8.7	2.7	9.4	9.8	ns
		V _{CC} = 1.65 V to 1.95 V	2.5	4.5	7.1	2.3	7.9	8.3	ns
		V _{CC} = 2.3 V to 2.7 V	2.4	3.8	5.3	2.2	5.9	6.2	ns
		V _{CC} = 3.0 V to 3.6 V	2.3	3.5	4.6	1.9	4.9	5.1	ns
C _L = 15 pF									
t _{pd}	propagation delay	nA, nB and nC to nY; see Figure 12							
		V _{CC} = 0.8 V	-	29.9	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.6	8.3	16.1	3.3	16.7	17.0	ns
		V _{CC} = 1.4 V to 1.6 V	3.0	5.9	9.7	3.0	10.5	11.0	ns
		V _{CC} = 1.65 V to 1.95 V	2.8	5.0	7.9	2.5	8.7	9.2	ns
		V _{CC} = 2.3 V to 2.7 V	2.7	4.2	5.9	2.5	6.6	6.9	ns
		V _{CC} = 3.0 V to 3.6 V	2.5	3.9	5.2	2.2	5.5	5.8	ns
C _L = 30 pF									
t _{pd}	propagation delay	nA, nB and nC to nY; see Figure 12							
		V _{CC} = 0.8 V	-	38.0	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	4.5	10.5	20.8	4.1	21.9	24.1	ns
		V _{CC} = 1.4 V to 1.6 V	3.8	7.5	12.2	3.8	13.5	14.1	ns
		V _{CC} = 1.65 V to 1.95 V	3.4	6.3	10.0	3.1	11.2	11.9	ns
		V _{CC} = 2.3 V to 2.7 V	3.4	5.3	7.5	3.1	8.4	8.9	ns
		V _{CC} = 3.0 V to 3.6 V	3.3	5.0	6.6	2.9	7.1	7.4	ns

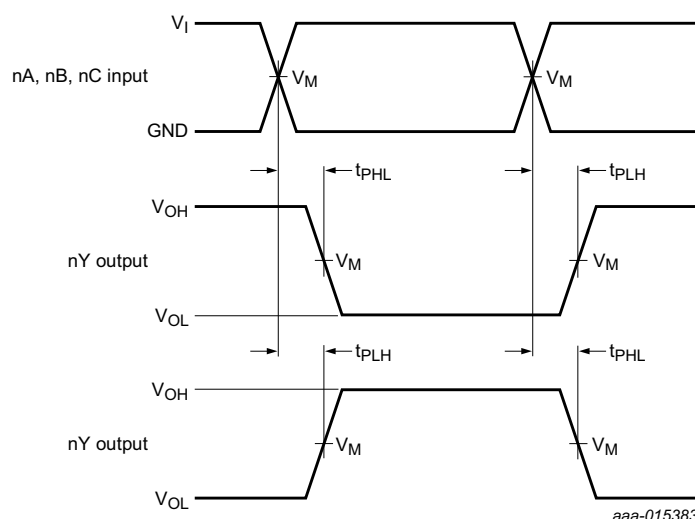
Table 9. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 13](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C _L = 5 pF, 10 pF, 15 pF and 30 pF									
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _I = GND to V _{CC} ^{[3][4]}							
		V _{CC} = 0.8 V	-	2.7	-	-	-	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	2.8	-	-	-	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	3.0	-	-	-	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	3.2	-	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	3.8	-	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	4.4	-	-	-	-	pF

- [1] All typical values are measured at nominal V_{CC}.
- [2] t_{pd} is the same as t_{PLH} and t_{PHL}.
- [3] All specified values are the average typical values over all stated loads.
- [4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

12. Waveforms



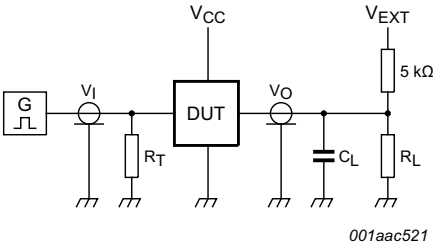
Measurement points are given in [Table 10](#).

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 12. Input nA, nB and nC to output nY propagation delay times

Table 10. Measurement points

Supply voltage	Output	Input		
V _{CC}	V _M	V _M	V _I	t _r = t _f
0.8 V to 3.6 V	0.5 × V _{CC}	0.5 × V _{CC}	V _{CC}	≤ 3.0 ns



Test data is given in [Table 11](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 13. Test circuit for measuring switching times

Table 11. Test data

Supply voltage	Load		V _{EXT}		
V _{CC}	C _L	R _L ^[1]	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	2 × V _{CC}

[1] For measuring enable and disable times, R_L = 5 kΩ, for measuring propagation delays, setup and hold times and pulse width R_L = 1 MΩ.

13. Transfer characteristics

Table 12. Transfer characteristics

Voltages are referenced to GND (ground = 0 V; for test circuit, see [Figure 13](#)).

Symbol	Parameter	Conditions	25 °C			–40 °C to +125 °C			Unit
			Min	Typ	Max	Min	Max (85 °C)	Max (125 °C)	
V_{T+}	positive-going threshold voltage	see Figure 14 and Figure 15							
		$V_{CC} = 0.8 \text{ V}$	0.30	-	0.60	0.30	0.60	0.62	V
		$V_{CC} = 1.1 \text{ V}$	0.53	-	0.90	0.53	0.90	0.92	V
		$V_{CC} = 1.4 \text{ V}$	0.74	-	1.11	0.74	1.11	1.13	V
		$V_{CC} = 1.65 \text{ V}$	0.91	-	1.29	0.91	1.29	1.31	V
		$V_{CC} = 2.3 \text{ V}$	1.37	-	1.77	1.37	1.77	1.80	V
		$V_{CC} = 3.0 \text{ V}$	1.88	-	2.29	1.88	2.29	2.32	V
V_{T-}	negative-going threshold voltage	see Figure 14 and Figure 15							
		$V_{CC} = 0.8 \text{ V}$	0.10	-	0.60	0.10	0.60	0.60	V
		$V_{CC} = 1.1 \text{ V}$	0.26	-	0.65	0.26	0.65	0.65	V
		$V_{CC} = 1.4 \text{ V}$	0.39	-	0.75	0.39	0.75	0.75	V
		$V_{CC} = 1.65 \text{ V}$	0.47	-	0.84	0.47	0.84	0.84	V
		$V_{CC} = 2.3 \text{ V}$	0.69	-	1.04	0.69	1.04	1.04	V
		$V_{CC} = 3.0 \text{ V}$	0.88	-	1.24	0.88	1.24	1.24	V
V_H	hysteresis voltage	$(V_{T+} - V_{T-})$; see Figure 14 , Figure 15 , Figure 16 and Figure 17							
		$V_{CC} = 0.8 \text{ V}$	0.07	-	0.50	0.07	0.50	0.50	V
		$V_{CC} = 1.1 \text{ V}$	0.08	-	0.46	0.08	0.46	0.46	V
		$V_{CC} = 1.4 \text{ V}$	0.18	-	0.56	0.18	0.56	0.56	V
		$V_{CC} = 1.65 \text{ V}$	0.27	-	0.66	0.27	0.66	0.66	V
		$V_{CC} = 2.3 \text{ V}$	0.53	-	0.92	0.53	0.92	0.92	V
		$V_{CC} = 3.0 \text{ V}$	0.79	-	1.31	0.79	1.31	1.31	V

14. Waveforms transfer characteristics

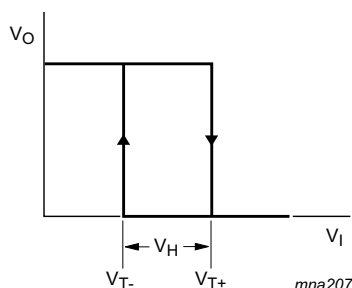
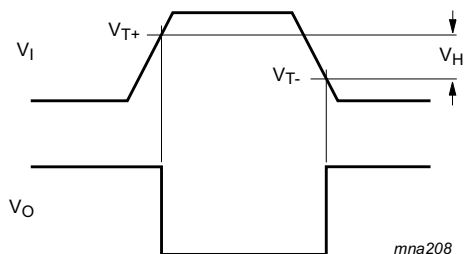


Fig 14. Transfer characteristic



V_{T+} and V_{T-} limits at 70 % and 20 %.

Fig 15. Definition of V_{T+} , V_{T-} and V_H

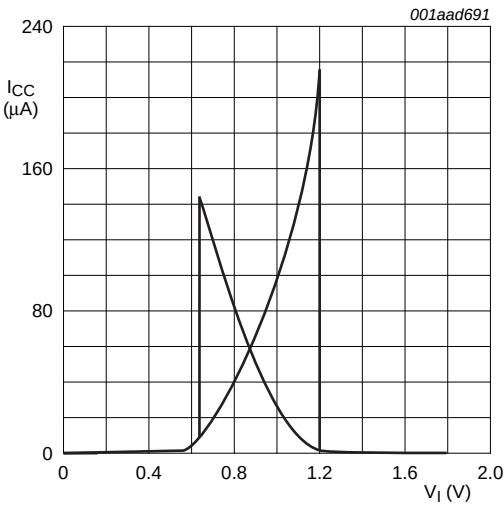


Fig 16. Typical transfer characteristics; $V_{CC} = 1.8\text{ V}$

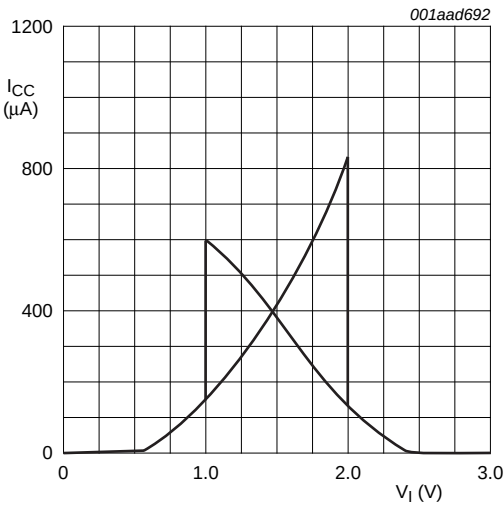


Fig 17. Typical transfer characteristics; $V_{CC} = 3.0\text{ V}$

15. Package outline

TSSOP10: plastic thin shrink small outline package; 10 leads; body width 3 mm

SOT552-1

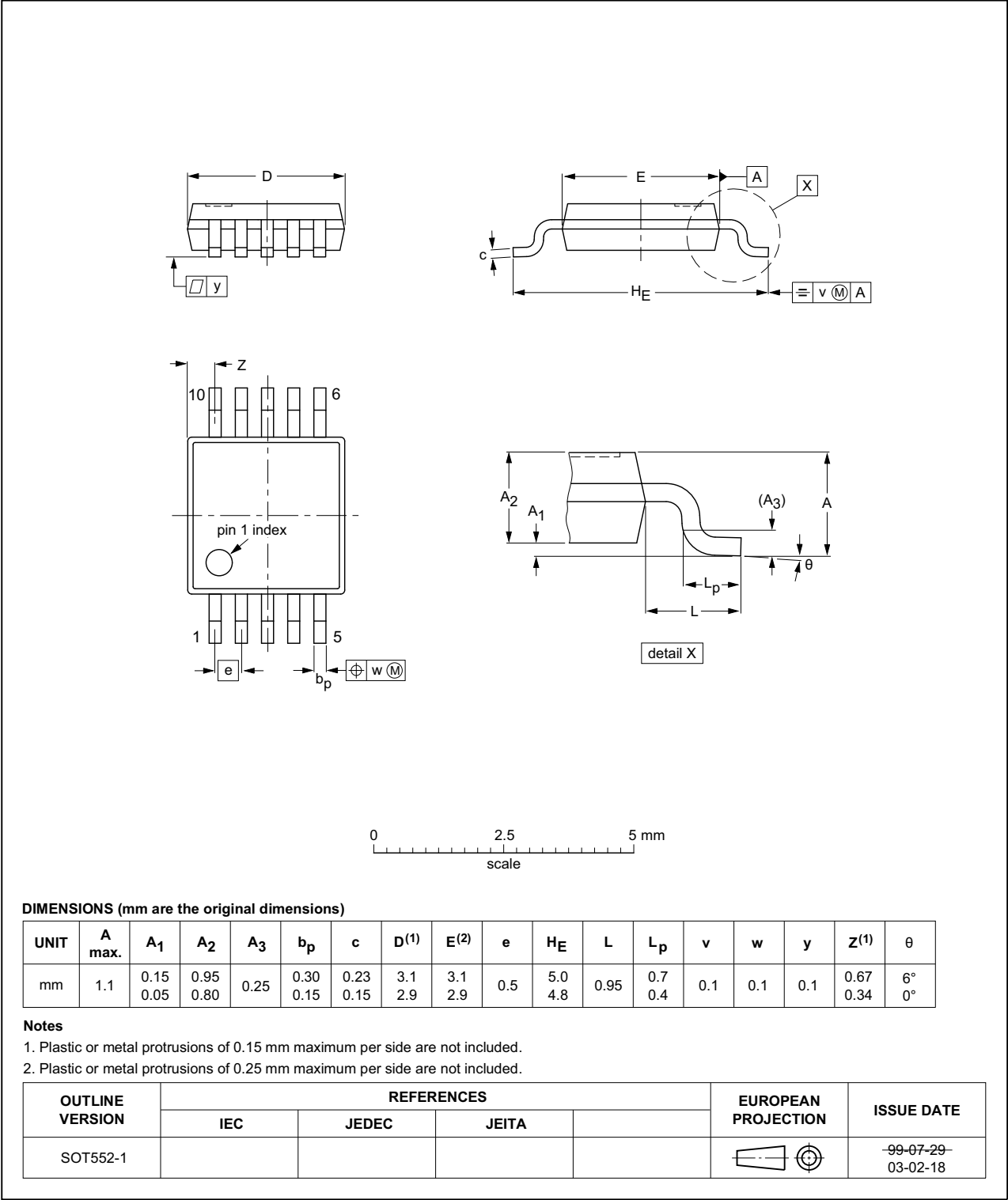


Fig 18. Package outline SOT552-1 (TSSOP10)

XQFN10: plastic, extremely thin quad flat package; no leads;
10 terminals; body 1.40 x 1.80 x 0.50 mm

SOT1160-1

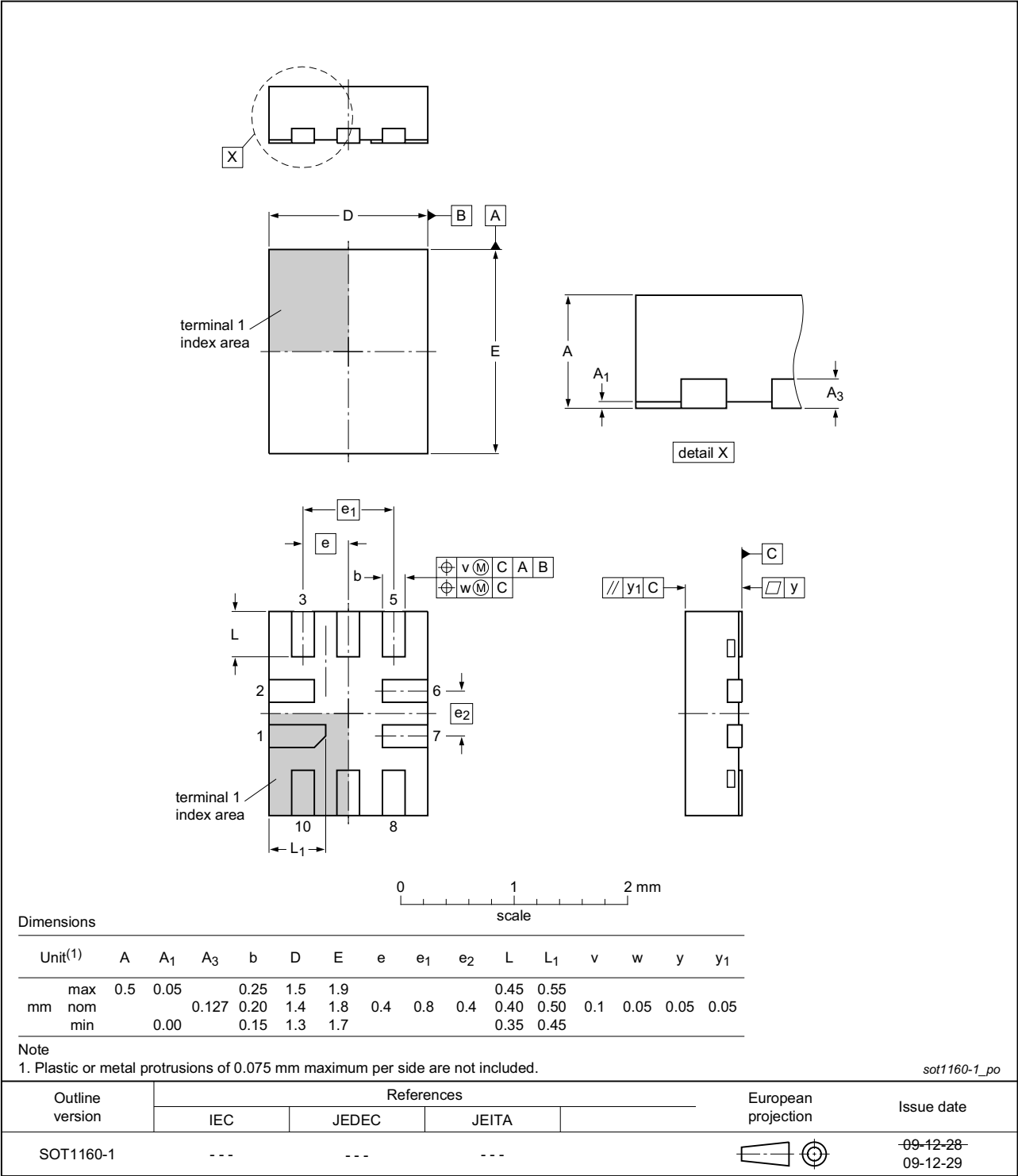


Fig 19. Package outline SOT1160-1 (XQFN10)

XSON10: plastic extremely thin small outline package; no leads;
10 terminals; body 1.0 x 1.7 x 0.5 mm

SOT1081-2

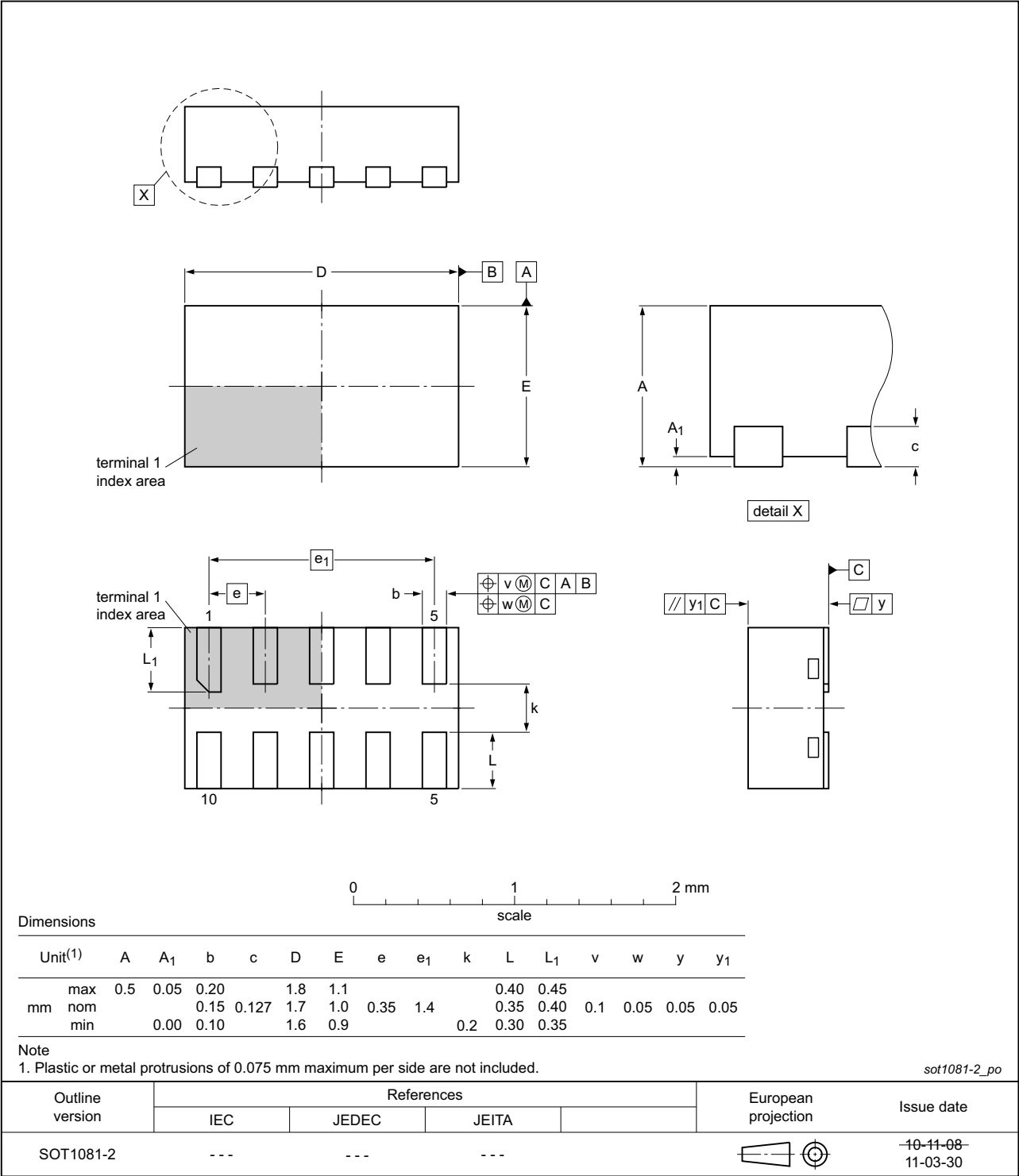


Fig 20. Package outline SOT1081-2 (XSON10)

16. Abbreviations

Table 13. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
PCB	Printed-Circuit Board

17. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP2G58 v.2	20151202	Product data sheet	-	74AUP2G58 v.1
Modifications:	- Maximum value temperature range TSSOP10 (74AUP2G58DP) changed from 85 °C to 125 °C. - Removed 74AUP2G58GM (SOT1049-3).			
74AUP2G58 v.1	20141104	Product data sheet	-	-

18. Legal information

18.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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20. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	2
4	Marking	2
5	Functional diagram	2
6	Pinning information	3
6.1	Pinning	3
6.2	Pin description	4
7	Functional description	4
7.1	Logic configurations	4
8	Limiting values	6
9	Recommended operating conditions	6
10	Static characteristics	7
11	Dynamic characteristics	10
12	Waveforms	11
13	Transfer characteristics	13
14	Waveforms transfer characteristics	13
15	Package outline	15
16	Abbreviations	18
17	Revision history	18
18	Legal information	19
18.1	Data sheet status	19
18.2	Definitions	19
18.3	Disclaimers	19
18.4	Trademarks	20
19	Contact information	20
20	Contents	21

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